Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: B= .015” X .070” E = .014” X .058”**

**Backside Potential: Collector**

**Mask Ref: PPC**

**APPROVED BY: DK DIE SIZE .122” X .122” DATE: 10/20/21**

**MFG: MICROSEMI (PPC) THICKNESS .020” P/N: 2N4150**

**DG 10.1.2**

#### Rev B, 7/19/02